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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/646,144	08/22/2003	Arnon Gat	AGX-27-DIV	8736
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GREENVILLI	E, SC 27002 1447		2823	
			DATE MAILED: 10/26/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/646,144	GAT, ARNON				
Office Action Summary	Examiner	Art Unit				
	Fernando L. Toledo	2823				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address						
Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply of 18 NO period for reply is specified above, the maximum statutory period of 19 Failure to reply within the set or extended period for reply will, by statute any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time y within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
 Responsive to communication(s) filed on <u>09 August 2004</u>. This action is FINAL. 2b) This action is non-final. Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i>, 1935 C.D. 11, 453 O.G. 213. 						
Disposition of Claims						
 4) Claim(s) 22-44 is/are pending in the application 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 22-44 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or 	wn from consideration.					
Application Papers						
9)☐ The specification is objected to by the Examine 10)☒ The drawing(s) filed on 22 August 2003 is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11)☐ The oath or declaration is objected to by the Examine 11.	a) accepted or b) objected to drawing(s) be held in abeyance. See tion is required if the drawing(s) is objected to a second control of the drawing of the d	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some color None of: Certified copies of the priority documents have been received. Certified copies of the priority documents have been received in Application No. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 20040809.	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	•				

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- Claims 22 44 are rejected under 35 U.S.C. 102(b) as being anticipated by Nakos et al.
 (U. S. Patent 5,226,732 A).

In re claims 22 and 44, Nakos, in the U. S. Patent 5,226,732 A; figures 1 – 4 and related text, discloses placing a semiconductor wafer 26 in a substrate holder 18 contained in a thermal processing chamber 10; rapidly heating the semiconductor wafer to a predetermined temperature using a heat source 30; and cooling the semiconductor wafer using an active cooling device 32, the cooling device including a cooling member maintained at a temperature lower than the wafer; wherein the cooling member defines one or more cooling channels for circulating a cooling fluid therethrough and defines one or more gas passages for flowing a cooling gas therethrough; and wherein the gas passage are configured to direct the cooling gas towards the semiconductor wafer and the substrate holder so that the cooling gas contact the semiconductor wafer and cools the wafer (Figure 1).

3. In re claim 23, Nakos discloses wherein the cooling gas is cooled by the cooling member (Column 3, Lines 53 - 61).

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- 4. In re claim 24, Nakos discloses wherein the cooling gas is cooled by the cooling fluid circulating through the cooling channels (Column 3, Lines 53 61).
- 5. In re claim 25, Nakos discloses wherein the cooling fluid is a liquid (Column 3, Lines 53 61).
- 6. In re claim 26, Nakos discloses wherein the liquid is water (Column 3, Lines 53 61).
- 7. In re claim 27, Nakos discloses wherein the cooling fluid is a gas (Column 3, Lines 53 61).
- 8. In re claim 28, Nakos discloses further including adjusting the flow of the cooling gas through the one or more gas passages for controlling the cooling of the semiconductor wafer (Column 3, Lines 53 61).
- 9. In re claim 29, Nakos discloses further including adjusting the circulation of the cooling fluid through the one or more cooling channels for controlling the cooling of the semiconductor wafer (Figure 1).
- 10. In re claim 30, Nakos discloses wherein the cooling device selectively cools the semiconductor wafer (Figure 1).
- 11. In re claim 31, Nakos discloses wherein the cooling device is stationary relative to the semiconductor wafer and the substrate holder (Figure 1).
- 12. In re claim 32, Nakos discloses wherein the cooling device is movable relative to the semiconductor wafer and the substrate holder (Figure 1).
- 13. In re claim 33, Nakos discloses wherein the substrate holder is adapted to hold and rotate the semiconductor wafer (Figure 1).

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- 14. In re claims 34 and 44, Nakos discloses wherein the heat source includes one or more lamps (Figure 1).
- 15. In re claim 35, Nakos discloses wherein the cooling gas is an inert gas (Column 3, Lines 53-61).
- 16. In re claim 36, Nakos discloses wherein the cooling gas is molecular nitrogen, argon or helium (Column 3, Lines 53 61).
- 17. In re claim 37, Nakos discloses further includes comprising monitoring the temperature of the semiconductor wafer while the wafer is in the thermal processing chamber (Figure 1).
- 18. In re claims 38 and 44, Nakos discloses wherein a temperature sensing device 48 monitors the temperature of the semiconductor wafer (Column 4, Lines 30 33).
- 19. In re claim 39, Nakos discloses wherein the temperature sensing device is configured to monitor the temperature of the semiconductor wafer at a single location on the wafer or at several locations on the wafer (Figure 1).
- 20. In re claim 40, Nakos discloses wherein the temperature sensing device is in communication with a controller, and wherein the controller receives temperature information form the temperature sensing device and, based on the information, controls the heating and cooling of the semiconductor wafer (Figure 2).
- 21. In re claim 41, Nakos discloses wherein the controller is in communication with the heat source, and wherein the controller receives temperature information form the temperature sensing device and, based on the information controls the heat source for controlling the heating of the semiconductor wafer (Column 4, Lines 19-30).

22. In re claim 42, Nakos discloses wherein the cooling device further includes a gas source for supplying the gas to the one or more gas passages, the gas source being in communication with the controller such that the controller is configured to control the flow gas from the gas source to the gas passage for controlling the cooling of the semiconductor wafer (Column 4, Lines 19-30).

23. In re claim 43, Nakos discloses wherein the controller controls the flow of gas from the gas source to the gas passage based on temperature information received from the temperature sensing device (Column 4, Lines 19 - 30).

Response to Arguments

24. Applicant's arguments with respect to claims 22 – 44 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

25. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37

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CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

however, will the statutory period for reply expire later than SIX MONTHS from the date of this

final action.

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Fernando L. Toledo whose telephone number is 571-272-1867.

The examiner can normally be reached on Mon-Thu 7am to 5:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the

organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent

Application Information Retrieval (PAIR) system. Status information for published applications

may be obtained from either Private PAIR or Public PAIR. Status information for unpublished

applications is available through Private PAIR only. For more information about the PAIR

system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR

system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

George Fourson
Primary Examiner

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FToledo

19 October 2004